Call for Nominations: Avram Bar-Cohen Memorial Medal – 2026

The Avram Bar-Cohen Memorial Medal is to honour a distinguished member of the electronic packaging community, Prof. Avram Bar-Cohen. In keeping with tradition, the award will continue to be given to a single individual at each InterPACK Conference. The same format will continue for this year's award with the winner to be announced prior to the InterPACK 2026 Conference, to be held in San Diego, CA, USA, October 26-29, 2026.

Prof. Avram Bar-Cohen

Nominations are solicited for the 2026 Avram Bar-Cohen Memorial Medal. Candidates must have demonstrated excellence over years and international recognition in the areas of research and development related to electronic packaging. They must also have a high level of service accomplishments to the technical community at large. Scientific and technical leadership is demonstrated by multiple means, including but not limited to publications, patents, technology and product development, and academic advising.

The nomination package should include:
1. A nomination letter with justification of the candidacy; no more than two pages.
2. Three additional letters of support.
3. Detailed curriculum vitae of the nominee.

Please submit the nomination package through the relevant ASME Awards website by clicking the "Submit Nomination Here" button, by 11:59 PM US Pacific Time, **March 1, 2026**.

Past nominees but non-winners will be grandfathered for two years beyond the original year of nomination. Any nominee that has gone through three cycles of the Award process will have to wait out one year before renomination. Incomplete nominations, or those submitted after the deadline will not be considered.

Past winners include:
- 2022 Prof. Pradeep Lall, Auburn University
- 2023 Dr. Sreekant Narumanchi, National Renewable Energy Laboratory
- 2024 Dr. John Lau, Unimicron Technology Corporation
- 2025 Dr. H Peter de Bock, Eaton Corporation